

Title (en)

Method for Manufacturing Electronic Parts Device and Resin Composition for Electronic Parts Encapsulation

Title (de)

Verfahren zur Herstellung einer Elektroteilvorrichtung und Harzzusammensetzung zur Elektroteilverkapselung

Title (fr)

Procédé de fabrication de dispositif à pièces électroniques et composition de résine pour encapsulation de pièces électroniques

Publication

EP 2426707 A1 20120307 (EN)

Application

EP 11180025 A 20110905

Priority

JP 2010198623 A 20100906

Abstract (en)

The present invention relates to a method for manufacturing an electronic parts device allowing for easy overmolding and underfilling, without requiring a jig for preventing leakage of the melted resin composition, and a resin composition sheet for electronic parts encapsulation used therein.

IPC 8 full level

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CPC (source: EP KR US)

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Citation (applicant)

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Designated contracting state (EPC)

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